

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims

1-37. (Cancelled)

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38. (Currently amended) The article of claim ~~37~~ 43 wherein the adhesive is selected from the group comprising hot melt adhesives, pressure sensitive adhesives, curable adhesives, and filled adhesives.

39. (Currently amended) The article of claim 38 wherein the filled adhesive is selected from the group comprising electrically conductive adhesives, thermally conductive adhesives, and ~~desiccating~~ desiccating adhesives.

40. (Currently amended) The article of claim ~~37~~ 43 wherein the circumference of the adhesive layer is greater than that of an electrode.

41. (Currently amended) The article of claim ~~37~~ 43 wherein the article is an organic light emitting diode.

42. (Currently amended) The article of claim ~~37~~ 44 wherein the substrate comprises glass, the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolino)aluminum, the electron transporting layer comprises bis(10-hydroxy-benzo(h)quinolino) beryllium, bis(2-(2-hydroxy-phenyl)-benzothiazolato) zinc, 3,4,5-triphenyl-1,2,4-triazole, or 2-(4-biphenyl)-5-(4-*t*-butylphenyl)-1,3,4-oxadiazole, and the cathode comprises lithium fluoride and aluminum.

43. (New) An article comprising an organic electronic device which comprises:

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- a. a substrate;
 - b. an adhesive on the substrate;

c. a multi-layer structure comprising one or more organic layers between an anode and a cathode, wherein the adhesive surrounds the multi-layer structure;

d. a sealing layer; and

wherein the adhesive is equal to the circumference of one or both of the substrate or sealing layer.

44. (New) The article of claim 43 wherein the organic layers comprise a hole transporting layer, a light emitting layer, and an electron transporting layer.

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